

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	435/dig2.ccls.	US-PGPUB; USPAT	OR	OFF	2005/11/22 14:17
S1	2	lustig-steven.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/11/17 07:30
S2	33	lustig-s.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/11/17 07:30
S3	690	lustig.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/11/22 07:05
S4	0	foggin-gary.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/11/17 07:29
S5	0	foggin-g.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/11/17 07:29
S6	12	foggin.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/11/17 07:31
S7	1	agreen-robert.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/11/17 07:34
S8	1	agreen-r.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/11/17 07:30

S9	8	agreen.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/11/17 07:35
S10	3669	dupont.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/11/17 07:46
S11	87	(S3 S6 S9 S10) and (chemical near3 (react\$3 analysis analyz\$3 analys\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 07:49
S12	69	(S3 S6 S9 S10) and (chemical near3 (react\$3 analysis analyz\$3 analys\$3))	USPAT	OR	ON	2005/11/17 07:52
S19	1649	(cylind\$5 with react\$3 near3 (housing enclosure shell))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 07:58
S20	877219	bore	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 07:55
S21	218036	central near3 axis	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 07:56
S23	49	S19 and S20 and S21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 07:58
S24	20	(cylind\$5 with chemical near3 react\$3 near3 (housing enclosure shell))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 07:59
S29	134028	(react\$3 near3 (section part module))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 08:02

S30	330449	(driv\$3 near3 (section part module))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 08:02
S31	15685	distribut\$3 near3 manifold	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 08:04
S35	12839	g01n021/64.ipc.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 08:23
S36	315	g01n021/52.ipc.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 08:24
S37	532	b01j019/00	US-PGPUB; USPAT	OR	ON	2005/11/17 08:23
S38	11442	g01n033/00.ipc.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 08:25
S39	1	wo-200029844-\$ did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 08:26
S40	1	wo-200051720-\$ did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 09:11
S41	1	wo-200107896-\$ did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 08:28
S42	1	gb-1548488-\$ did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 08:29

S43	2	ep-1226867-.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 08:29
S44	122402	((test\$3 analy\$4 measur\$5) with (group plural several many collection set plurality numerous assortment) with (sample specimen wafer die dice semiconductor (integrated near3 circuit)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 09:15
S45	869	((test\$3 analy\$4 measur\$5) with (group plural several many collection set plurality numerous assortment) with (sample specimen wafer die dice semiconductor (integrated near3 circuit))) and ((fluid liquid gas plasma) with distribut\$3) and (holder mount container) and (analyzer analyser)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 09:23
S46	20664	(react\$3 near3 (chamber vessel enclosure)) and analy\$4 and (holder container)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 11:04
S47	780	(react\$3 near3 (chamber vessel enclosure)) and analy\$4 and ((holder container) same (slide slideable sliding))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 11:41
S48	40	(react\$3 near3 (chamber vessel enclosure)) same analy\$4 same (((wafer specimen sample die dice semiconductor) with (holder container tray table platen platform plate)) same (slide slideable sliding))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 09:38
S49	27	((fluid liquid gas plasma) with (distribut\$3 dispers\$3) with (system mechanism machine tool)) and (slid\$4 with (holder mount container)) and (analyzer analyser)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 10:41
S50	99	(((fluid liquid gas plasma) with (distribut\$3 dispers\$3) with (system mechanism machine tool)) (reaction near3 (chamber enclosure))) and (slid\$4 with (holder mount container)) and (analyzer analyser)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 10:20

S51	67	(((fluid liquid gas plasma) with (distribut\$3 dispers\$3) with (system mechanism machine tool)) (reaction near3 (chamber enclosure))) and (slid\$4 with (holder mount container)) and (analyzer analyser) and ((plurality several group plural many numerous collection) with (sample specimen wafer die dice semiconductor (integrated near3 circuit)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 10:26
S53	288	436/46.ccls.	US-PGPUB; USPAT	OR	OFF	2005/11/17 10:41
S54	496	436/47.ccls.	US-PGPUB; USPAT	OR	OFF	2005/11/17 10:41
S55	311	702/30.ccls.	US-PGPUB; USPAT	OR	OFF	2005/11/17 10:42
S56	180	702/31.ccls.	US-PGPUB; USPAT	OR	OFF	2005/11/17 10:42
S60	453	"438"/\$.ccls. and ((reactor reaction etch etching) near3 (chamber vessel enclosure)) and analy\$4 and ((sample specimen wafer die dice semiconductor (integrated near3 circuit)) near3 (holder container table tray plate platen))	US-PGPUB; USPAT	OR	ON	2005/11/17 11:15
S61	1979	438/14.ccls.	US-PGPUB; USPAT	OR	ON	2005/11/17 11:15
S62	900	438/16.ccls.	US-PGPUB; USPAT	OR	ON	2005/11/17 11:16
S63	453	216/58.ccls.	US-PGPUB; USPAT	OR	ON	2005/11/17 11:16
S64	353	216/59.ccls.	US-PGPUB; USPAT	OR	ON	2005/11/17 11:16
S65	311	216/60.ccls.	US-PGPUB; USPAT	OR	ON	2005/11/17 11:17
S66	27	(S35 S36 S37 S38 S63 S54 S55 S56 S61 S62 S63 S64 S65) and ((group set subset subgroup portion all entire part whole entirety entirely complete completely) same (expose exposed exposing) same (fluid gas plasma liquid particulate) same simultaneously)	US-PGPUB; USPAT	OR	ON	2005/11/17 11:32
S68	1358	(((subset subgroup portion part partial partly) with (expose exposed exposing)) same (fluid gas plasma liquid particulate) same simultaneously)	US-PGPUB; USPAT	OR	ON	2005/11/17 11:36
S70	1156	((reactor reaction etch etching) near3 (chamber vessel enclosure)) and analy\$4 and ((slide slideable sliding) near4 (holder container table tray plate platform))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 11:44

S72	118085	(method methodology process procedure routine algorithm program scheme plan) and (test\$3 analy\$3 measur\$5) and (plurality several some numerous many plural group set collection assortment) and (sample specimen analyte wafer die dice semiconductor (integrated near3 circuit)) and simultaneous\$2 and react\$3 and (all entire whole entirety) and (fluid liquid plasma gas)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 14:31
S73	366	((method methodology process procedure routine algorithm program scheme plan) same (test\$3 analy\$3 measur\$5) same ((plurality several some numerous many plural group set collection assortment) with (sample specimen analyte wafer die dice semiconductor (integrated near3 circuit)))) and (simultaneous\$2 same react\$3 same (all entire whole entirety) same (fluid liquid plasma gas))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/17 14:41
S74	106	435/dig\$.ccls. and (combinatorial near3 chemistry)	US-PGPUB; USPAT	OR	ON	2005/11/22 14:17
S75	2022	436/164.ccls.	US-PGPUB; USPAT	OR	OFF	2005/11/17 14:58
S77	341	analy\$3 and ((plural several numerous plurality group collection assortment many) same ((specimen analyte sample wafer die dice substrate semiconductor (integrated near3 circuit)) with (holder table platen plate platform table))) and (((fluid liquid gas plasma) with (distribut\$3 disburs\$3)) (molecular near3 transport)) with system)	US-PGPUB; USPAT	OR	OFF	2005/11/17 15:44
S80	1203	(apparatus appliance tool device instrument machine mechanism) and (test testing tested measure measuring measurement measured analysing analyzing analysis) and (group set collection several plural many plurality numerous) and (sample specimen analyte wafer die dice) and ((fluid plasma gas liquid) with (distribution distribution distributing dispersal dispersing dispersement) with (system process procedure routine algorithm software firmware)) and (simultaneous simultaneously) and (expose exposure exposing) and (sample specimen analyte wafer die dice) and (fluid plasma gas liquid) and (holder tray table platen platform support) and (slide sliding slidable slidable move moving movement moveable translating translateable translation) and (relative respect) and (system process procedure routine algorithm software firmware) and (computer processor microcomputer microprocessor controller analyser analyzer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/21 08:28

S81	654	(apparatus appliance tool device instrument machine mechanism) and ((test testing tested measure measuring measurement measured analysing analyzing analysis) same (group set collection several plural many plurality numerous) same (sample specimen analyte wafer die dice)) and ((fluid plasma gas liquid) with (distribution distribution distributing dispersal dispersing dispersement) with (system process procedure routine algorithm software firmware)) and (simultaneous simultaneously) and (expose exposure exposing) and (sample specimen analyte wafer die dice) and (fluid plasma gas liquid) and (holder tray table platen platform support) and (slide sliding slidable slidably move moving movement moveable translating translateable translation) and (relative respect) and (system process procedure routine algorithm software firmware) and (computer processor microcomputer microprocessor controller analyser analyzer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/21 08:33
S82	147	(apparatus appliance tool device instrument machine mechanism) and ((test testing tested measure measuring measurement measured analysing analyzing analysis) same (group set collection several plural many plurality numerous) same (sample specimen analyte wafer die dice)) and ((fluid plasma gas liquid) with (distribution distribution distributing dispersal dispersing dispersement) with (system process procedure routine algorithm software firmware)) and (simultaneous simultaneously) and (expose exposure exposing) and (sample specimen analyte wafer die dice) and (fluid plasma gas liquid) and ((holder tray table platen platform support) same (slide sliding slidable slidably move moving movement moveable translating translateable translatable translation) same (relative respect)) and (computer processor microcomputer microprocessor controller analyser analyzer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/21 08:37

S83	50	(apparatus appliance tool device instrument machine mechanism) and ((test testing tested measure measuring measurement measured analysing analyzing analysis) same (group set collection several plural many plurality numerous) same (sample specimen analyte wafer die dice)) and ((fluid plasma gas liquid) with (distribution distribution distributing dispersal dispersing dispersement) with (system process procedure routine algorithm software firmware)) and ((simultaneous simultaneously) same (expose exposure exposing) same (sample specimen analyte wafer die dice)) and (fluid plasma gas liquid) and ((holder tray table platen platform support) same (slide sliding slidable slideable move moving movement moveable translating translateable translatable translation) same (relative respect)) and (computer processor microcomputer microprocessor controller analyser analyzer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/21 08:39
S90	504	((chemical vapor gas plasma liquid fluid) near3 (deposition etch etching etchant etcher depositor depositing)) and ((specimen sample wafer die dice) with (holder table tray plate platen support) with (slide sliding slidably slideable slider glider glide gliding glidably))	USPAT	OR	ON	2005/11/22 11:52
S91	242	((chemical vapor gas plasma liquid fluid) near3 (deposition etch etching etchant etcher depositor depositing)) and ((specimen sample wafer die dice) near5 (holder table tray plate platen support) near5 (slide sliding slidably slideable slider glider glide gliding glidably))	USPAT	OR	ON	2005/11/22 11:52
S92	195	((chemical vapor gas plasma liquid fluid) near3 (deposition etch etching etchant etcher depositor depositing)) and ((specimen sample wafer die dice) near3 (holder table tray plate platen support) near5 (slide sliding slidably slideable slider glider glide gliding glidably))	USPAT	OR	ON	2005/11/22 12:37
S93	228	(((specimen sample wafer die dice substrate) near3 (holder tray plate platen surface table support)) with (cover lid top closure door hatch)) and ((analyzer controller \$computer \$processor) same (cover lid top closure door hatch) same (slideable slide glide glidable sliding gliding) same (holder tray plate platen surface table support))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/22 12:35

S94	134	((specimen sample wafer die dice substrate) near3 (holder tray plate platen surface table support)) with (cover lid top closure door hatch) and ((analyzer controller \$computer \$processor) same (cover lid top closure door hatch) same (slideable slide glide glidable sliding gliding) same (holder tray plate platen surface table support))	USPAT	OR	ON	2005/11/22 12:38
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